

Copper

SLOTOCOUP CU 1370

Copper SLOTOCOUP CU 1370 is used for the production of printed circuit boards for automotive and base station applications. The electrolyte is operated with direct current and enables very good throwing power in high aspect ratio holes.

The layers deposited from Copper SLOTOCOUP CU 1370 are very bright. The electrolyte was particularly designed for operation in vertical continuous plating lines and high current densities (over 3 A/dm²).

Copper SLOTOCOUP CU 1370 is made-up with three liquid additives.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

